

In the Specification:

Please amend the paragraph appearing at page 5, lines 2-20, as follows:

Multi-chip modules (MCMs) are semiconductor devices with more than one die mounted on a substrate. During operation, these semiconductor devices generate heat that must be dissipated to allow the semiconductor device to continue functioning properly. Accordingly, current methods of heat dissipation include mounting a lid having cavities with substantially uniform dimensions corresponding to each die on the substrate. This lid or heat sink is generally mounted to the substrate so that the individual dies of the semiconductor device fit inside the cavities of the lid. Often, the individual dies on the substrate of an MCM or ASIC have varying heights and dimensions, thus resulting in gaps of varying sizes between the dies and the surface of the lid cavities. In order to dissipate heat from the dies to the heat sink link, epoxies are often used to fill the gaps between the dies and the cavity. Unfortunately, most epoxies have very poor thermally conductive properties. For example, most epoxies generally used to fill the space between the dies and the cavities have a thermal conductivity of between 1-8 W/m-°C. The lids, alternatively, have a thermal conductivity of approximately 150-400 W/m-°C. Accordingly, the amount of heat able to be dissipated by the heat sink lid is dependent on the ability of the epoxy between the lid cavity and the die of the semiconductor device to conduct heat or energy from the semiconductor device to the lid, and ~~upon~~ upon the thickness of the epoxy material.